

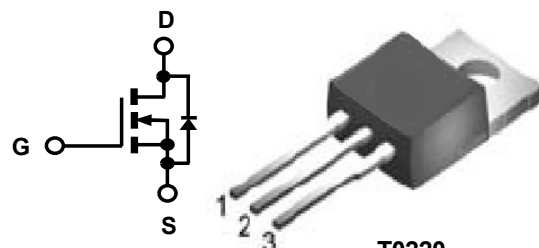
ICEK15NF65 N-Channel Enhancement Mode MOSFET

Features

- Low $r_{DS(on)}$
- Ultra Low Gate Charge
- High dv/dt capability
- High Unclamped Inductive Switching (UIS) capability
- High peak current capability
- Increased transconductance performance
- Optimized design for high performance power systems



Product Summary			
I_D	$T_A=25^\circ\text{C}$	15.1A	Max
$V_{(BR)DSS}$	$I_D=250\mu\text{A}$	650V	Min
$r_{DS(on)}$	$V_{GS}=10\text{V}$	0.165	Typ
Q_g	$V_{DS}=400\text{V}$	32nC	Typ



TO220

Standard Metal
Heatsink

1=Gate, 2=Drain,
3=Source.

Maximum ratings^a, at $T_j=25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current ^b	I_D	$T_c=25^\circ\text{C}$	15.1	A
		$T_c=100^\circ\text{C}$	9.5	
Pulsed drain current ^b	$I_{D, \text{pulse}}$	$T_c=25^\circ\text{C}$	60	A
Avalanche energy, single pulse	E_{AS}	$L = 75 \text{ mH}, V_{DD} = 100 \text{ V}, I_D=1.8\text{A}, R_G = 25 \Omega$	121.5	mJ
Avalanche current, repetitive ^b	I_{AR}	limited by $T_{j\text{max}}$	1.8	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=480\text{V}$	50	V/ns
Reverse diode dv/dt ruggedness			100	
Gate source voltage	V_{GS}	Static	± 30	V
		AC ($f>1\text{Hz}$)		
Power dissipation	P_{tot}	$T_c=25^\circ\text{C}$	113.6	W
Operating and storage temperature	T_j, T_{stg}		-55 to +150	$^\circ\text{C}$

^a Preliminary data sheet - Specifications subject to change.

^b limited by $T_{j\text{max}}$

^c when mounted on 1-inch square 2oz copper-clad FR-4

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Thermal characteristics

Thermal resistance, junction-case	R_{thJC}		-	-	1.1	°C/W
Thermal resistance, junction-ambient °	R_{thJA}	leaded	-	-	55	
Soldering temperature, wave soldering only allowed at leads	T_{sold}	1.6mm (0.063in.) from case for 10 s	-	-	260	°C

Electrical characteristics, at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	650	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.5	3.5	4.5	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	-	-	10	μA
Gate source leakage current	I_{GSS}	$V_{GS}=\pm 30\text{ V}, V_{DS}=0\text{V}$	-	-	± 100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=10\text{A}$	-	0.165	0.19	Ω
Gate resistance	R_G	$f=1\text{ MHz}$, open drain	-	17	-	Ω

Dynamic characteristics

Input capacitance	C_{iss}	$V_{DS}=400\text{ V}, V_{GS}=0\text{ V}, f=1\text{ MHz}$	-	910	-	pF
Output capacitance	C_{oss}		-	24	-	
Reverse transfer capacitance	C_{rss}		-	6.5	-	
Turn-on delay time	$t_{d(on)}$	$V_{DS}=400\text{V}, V_{GS}=10\text{V}, I_D=10\text{A}, R_G=2\Omega$ (External)	-	43	-	ns
Rise time	t_r		-	38	-	
Turn-off delay time	$t_{d(off)}$		-	72	-	
Fall time	t_f		-	9	-	

Parameter	Symbol	Conditions	Values			Unit
			Min	Typ	Max	

Gate charge characteristics

Gate to source charge	Q_{gs}	$V_{DS}=400\text{ V}, I_D=10\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	5	-	nC
Gate to drain charge	Q_{gd}		-	17	-	
Gate charge total	Q_g		-	32	-	

Reverse Diode

Continuous forward current	I_S	$V_{GS}=0\text{ V}$	-	-	15.1	A
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_S=I_F$	-	1.25	-	V
Reverse recovery time	t_{rr}	$V_{RR}=400\text{ V}, I_S=10\text{ A},$ $d_i I_F/d_t=200\text{ A}/\mu\text{S}$	-	66	-	ns
Reverse recovery charge	Q_{rr}		-	0.6	-	μC
Peak reverse recovery current	I_{rm}		-	12	-	A

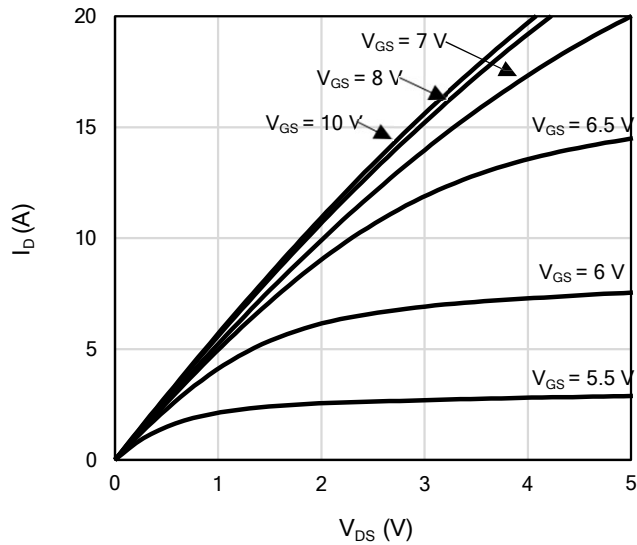


Figure 1: On-Region Characteristics

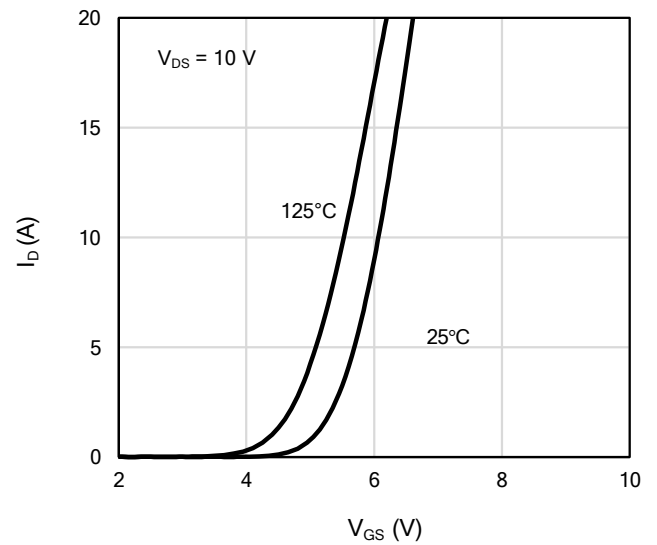


Figure 2: Transfer Characteristics

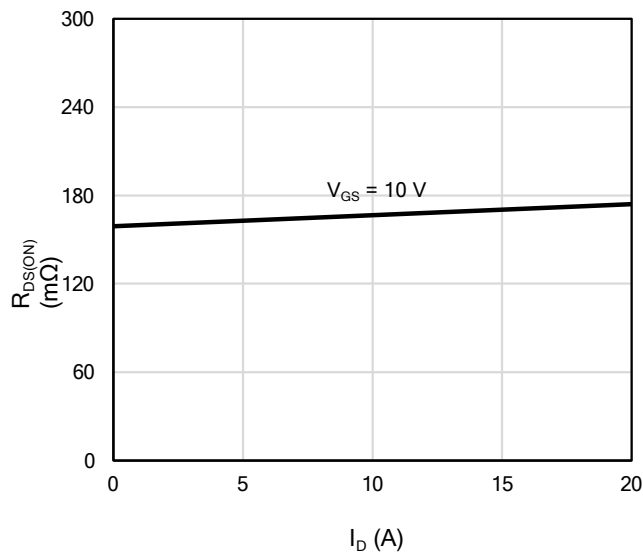


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

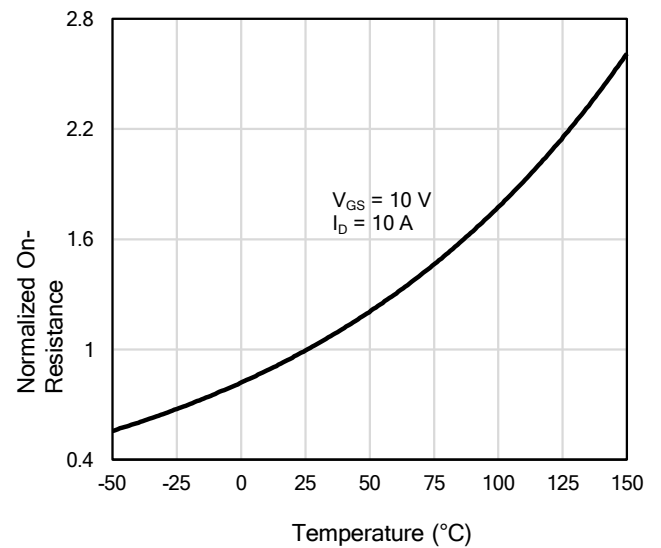


Figure 4: On-Resistance vs. Junction Temperature

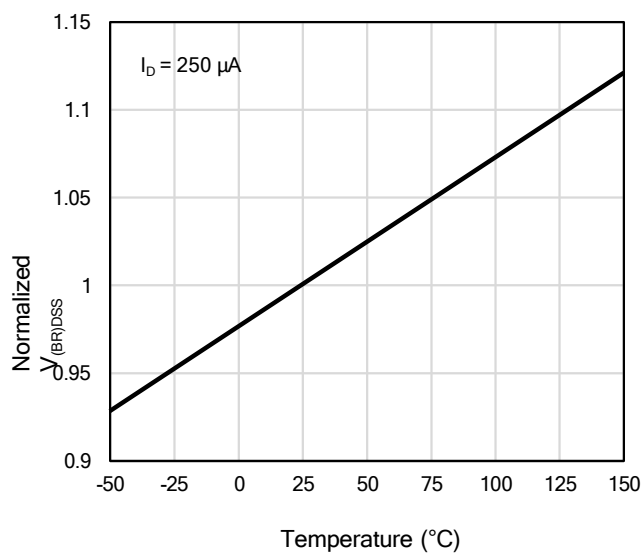


Figure 5: Breakdown Voltage vs. Junction Temperature

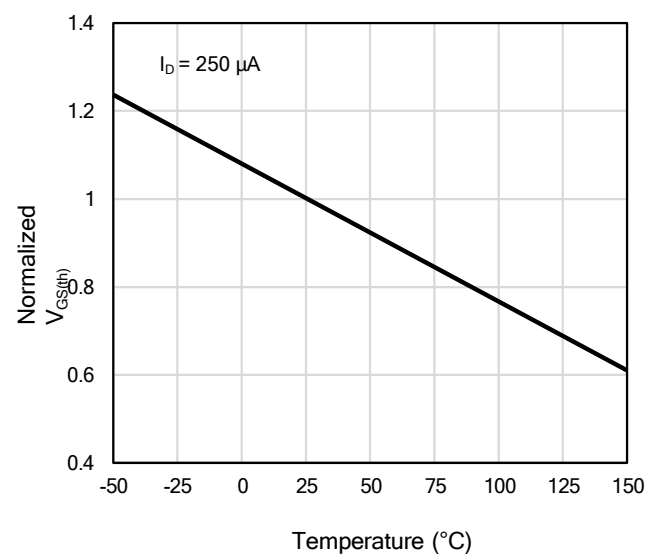


Figure 6: Threshold Voltage vs. Junction Temperature

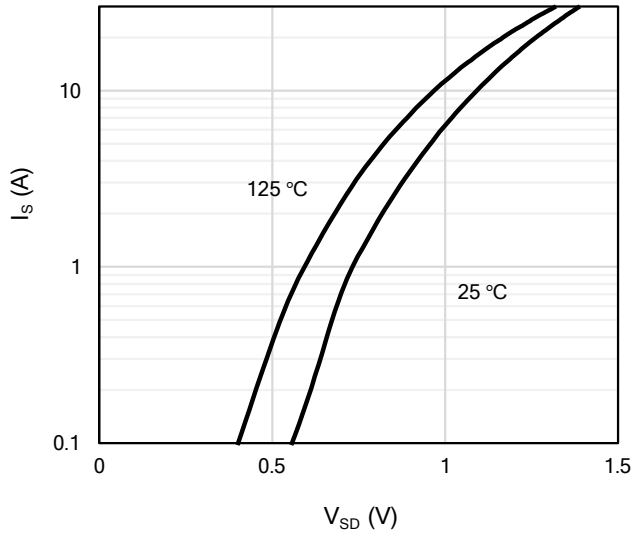


Figure 7: Body-Diode Characteristics

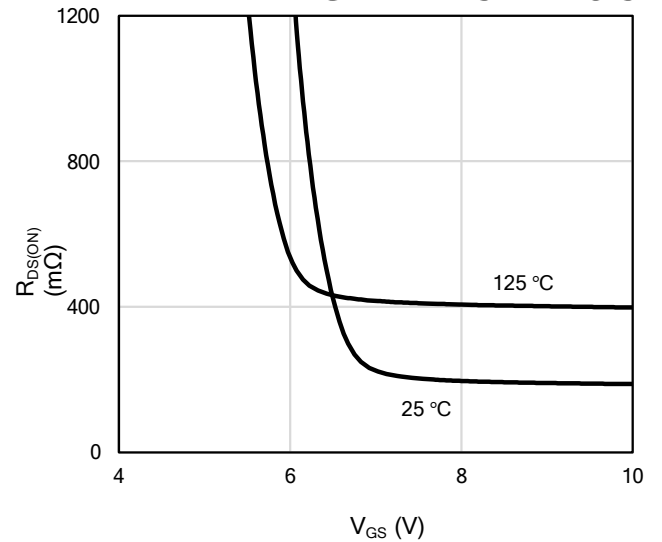


Figure 8: On-Resistance vs. Gate-Source Voltage

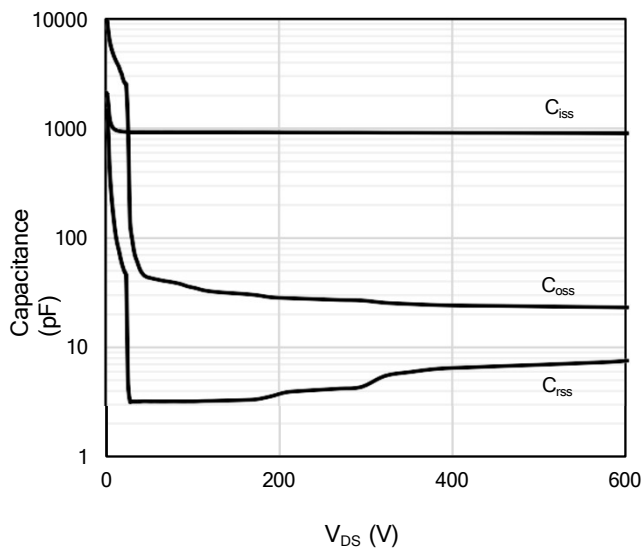


Figure 9: Capacitance Characteristics

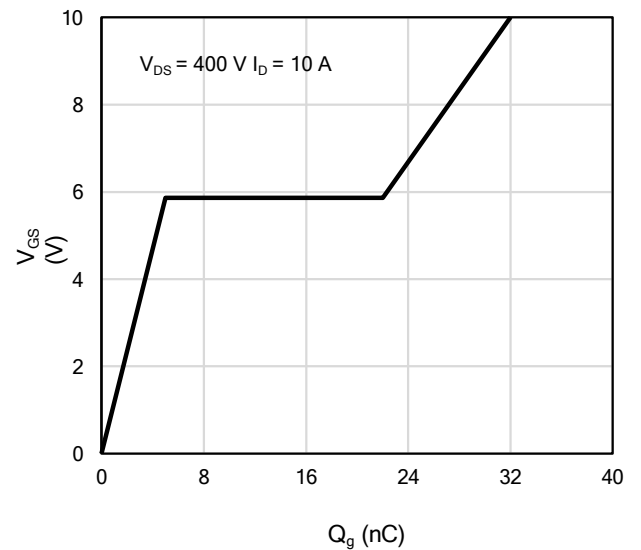


Figure 10: Gate-Charge Characteristics

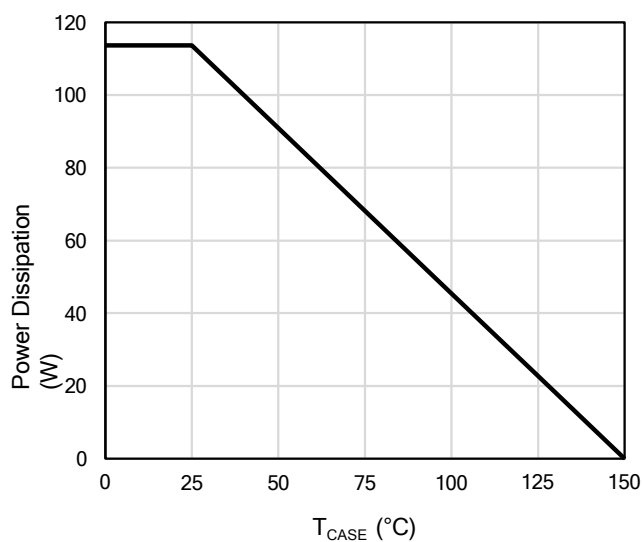


Figure 11: Power De-rating

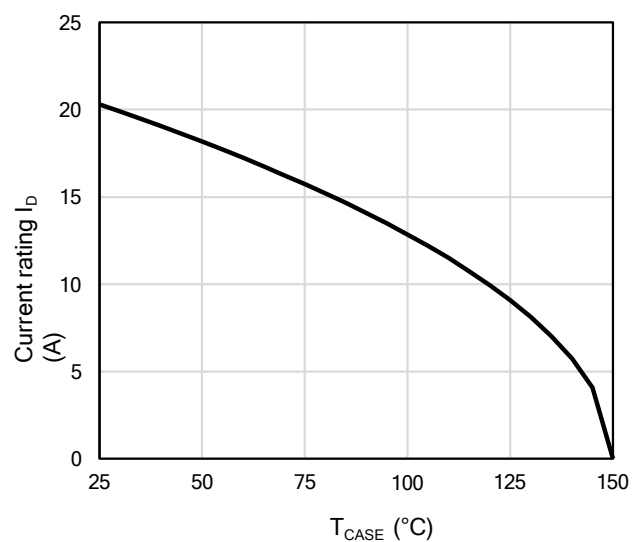


Figure 12: Current De-rating

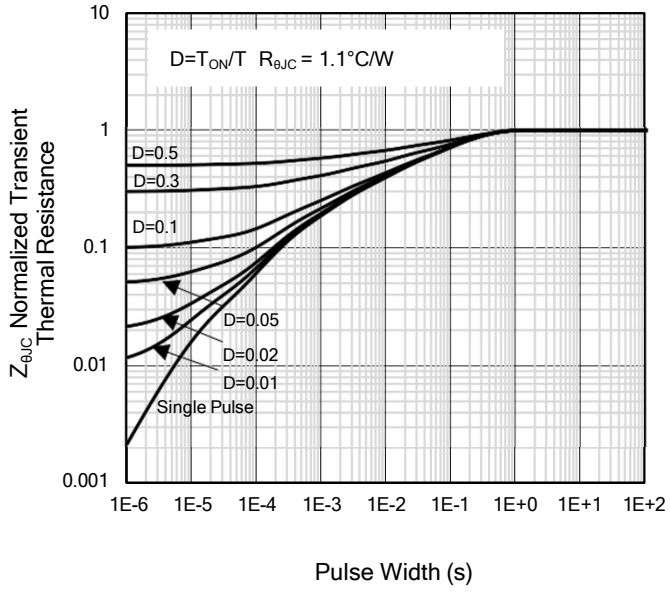


Figure 13: Normalized Maximum Transient Thermal Impedance

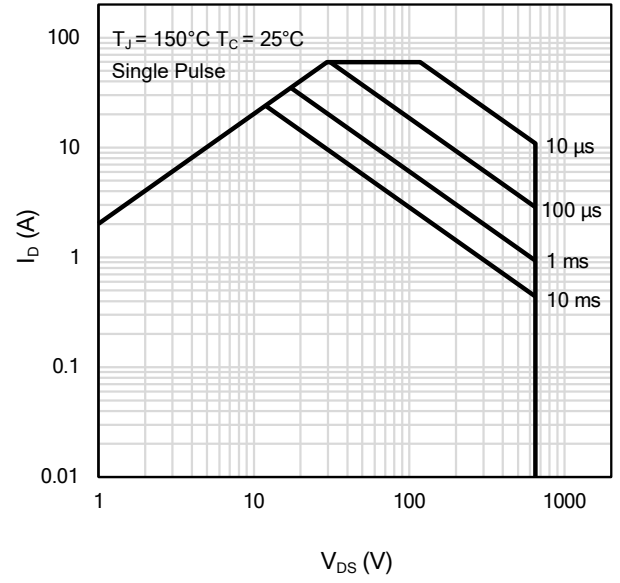


Figure 14: Maximum Forward Biased Safe Operating Area

Marking Information

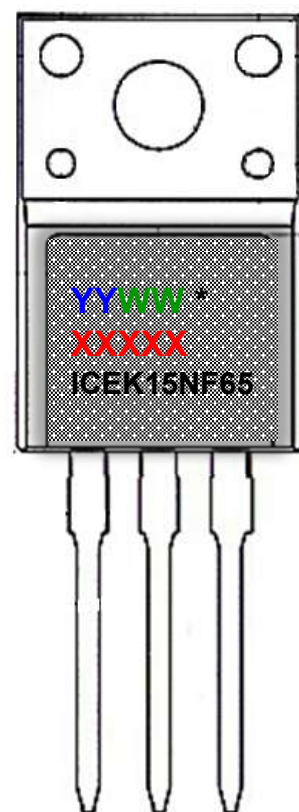
YY = Last two digits of the year

WW = Work week

***** = Site ID

XXXXXX = Lot ID

ICEK15NF65 = ICE is IceMOS logo and K15NF65 is a designated device part number



Disclaimer

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